

SFL-3E Dielectric

Features & Benefits

- Thermal resistance 100μm, 0.13°C-in²/W
- Product Thermal conductivity of 3 W/m-K
 - o (2oz Cu x 100μm SFL 3E x 1.5 Al)
- Low Modulus
- High Voltage Strength
- · Lead-free solder compatible
- Eutectic AuSn compatible
- · RoHS compliant and environmentally green
- Available as a laminated panel, RCC or prepreg
- Available on aluminum and copper base substrates
- 4045 aluminum alloy complements SFL 3E in improving solder joint reliability.

Thermal Clad SFL-3E laminates and prepregs are specifically designed to improve solder joint reliability as a result of CTE mismatch between the component package and the baseplate metal.

The differentiating technology of Thermal Clad resides in the dielectric. This datasheet highlights the performance characteristics of Thermal Clad SFL 3E.

Applications

 LED headlight & foglamps and other applications where ceramic based components are used and improved solder joint reliability is required.

Configurations

Base Metal

Thickness mm (mil)

- 5052 Aluminum 0.8 (32), 1.0 (40)*, 1.6 (63)*, 2.0 (80), 3.2 (125)
- 6061 Aluminum 0.8 (32), 1.0 (40)*, 1.6 (63)*, 2.0 (80), 3.2 (125), 4.8 (190)
- 4045 Aluminum 1.5 (59), 2.0 (80)
- Copper C1100 0.5 (20), 0.8 (32), 1.0 (40)*, 1.58 (62)*, 3.2 (125)

Copper Foil

Weight oz (thickness µm)

- ED Copper 1oz (35), 2oz (70), 3oz (105), 4oz (140), 6oz (210)
- RA 8oz (280), 10oz (350)
- * Most common thicknesses
- ** Other thicknesses and alloys may be available. Please contact TCLAD sales department for more information.

We provide custom solutions for your applications. For Further inquiries, please contact your local sales agent or directly to TCLAD sales sales@tclad.com

Thickness Unit **Item** Value (Typ.) **Method Thermal Properties Product Thermal Conductivity** W/m-K 3 TO-220 W/m-K **ASTM D5470** Dielectric Thermal Conductivity 1.6 Thermal <0.13 100µm (4mil) °C-in²/W **ASTM D5470** Resistance Thermal 100µm (4mil) °C/W 0.33 TO-220 Impedance **Electrical Properties** IPC-TM-650 Dielectric Constant 5.6 2.5.5.3 Dissipation IPC-TM-650 100µm (4mil) 1MHz 0.021 Factor 2.5.5.3 IPC-TM-650 100µm (4mil) Capacitance рF 28.21 2.5.5.3 IPC-TM-650 1015 Volume Resistivity Ω -cm 2.5.17.1 IPC-TM-650 1013 Surface Resistivity Ω/sq 2.5.17.1 5 80µm (2mil) Breakdown 7 100µm (4mil) **KVAC** ASTM D149 Voltage 9 150µm (6mil) **Mechanical Properties** Off-white Visual Color IPC TM-650 Peel Strength @ 25°C N/mm >1.4 2.4.8 IPC TN-650 Glass Transition (Tg °C 55 2..4.25 IPC TM-650 CTE in X,Y/Z Axis <Tg µm/m°C 24 24245 IPC TM-650 CTE in X,Y/Z Axis >Tg µm/m°C 37 2.4.24.5 **ASTM D4065 GPa** 0.5 Storage Modulus **Chemical Properties** ASTM E595 Water Absorption < 0.5 % Wt. ASTM E595 % Wt. <0.1 Out-Gassing Total Mass Loss Collect Volatile Condensable % Wt. < 0.1ASTM E595 Material **Agency Ratings & Durability UL Maximum Operating** °C 140 UL 746 Temperature (MOT) **UL Flammability** V-0 UL 94 ASTM D3638/ **UL Comparative Tracking Index** (CTI) 0/600 IEC 60112 °C Solder Limit Rating 325 UL 746

Test Thermal Performance of Insulated Metal Substrate (IMS®) TO-220 Set-up





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